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(54) Title: PROCESS STACK FOR CVD PLASMA TREATMENT

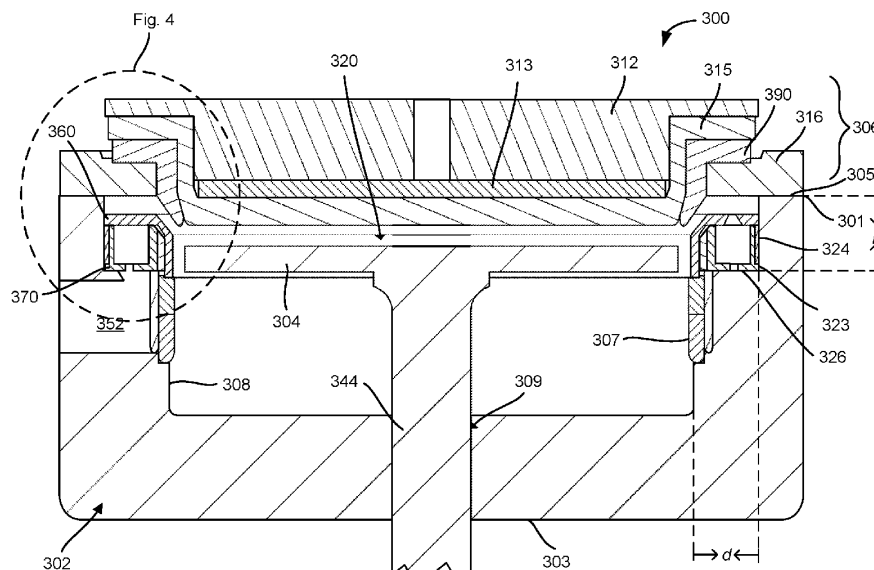


FIG. 3

(57) Abstract: Gas distribution assemblies, processing chambers, and methods for processing substrates are provided. A substrate processing chamber includes a chamber body having a first end and a second end, a lid coupled to the first end of the chamber body, an isolator disposed on an upper surface of the lid, a faceplate disposed on an upper surface of the isolator, a substrate support disposed on a shaft extending through the second end of the chamber body, a pumping ring positioned within the chamber body, and an exhaust outlet in fluid communication with a system foreline and the plurality of apertures. The processing chamber defines a processing region between the substrate support and the faceplate. The pumping ring includes a flange extending in a plane generally parallel with a top surface of the substrate support that defines a plurality of apertures.

[Continued on next page]

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